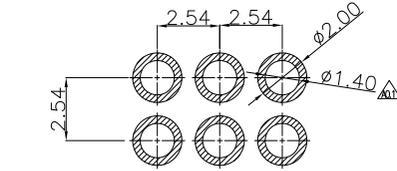
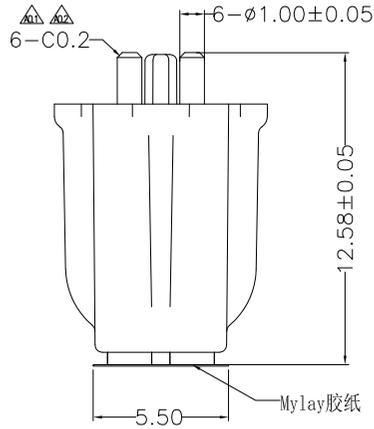


# GP Component

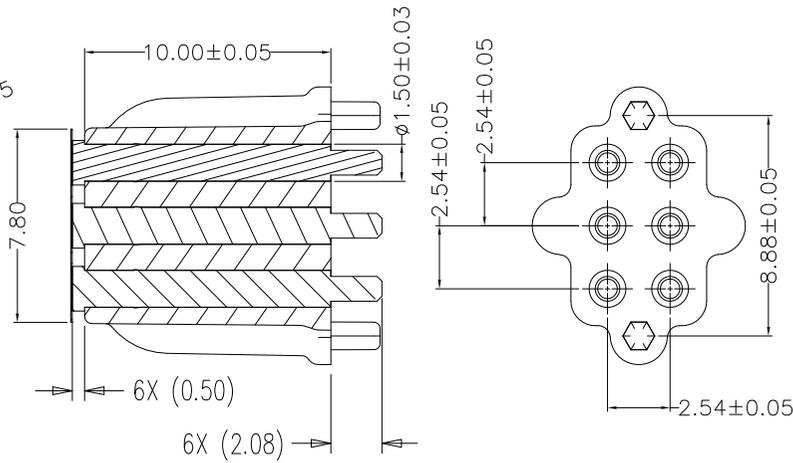
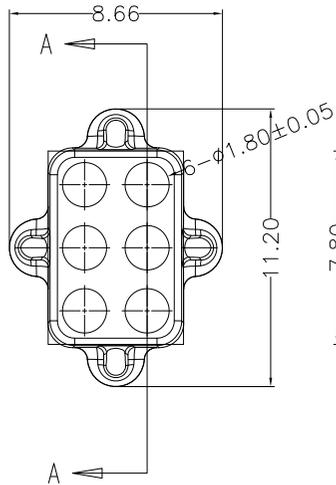
REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2022/12/01	Hanson
A0.1			Change DIM.	2023/02/15	Hanson
A0.2			Change DIM.	2023/03/23	Hanson



RECOMENMDED PCB LAYOUT

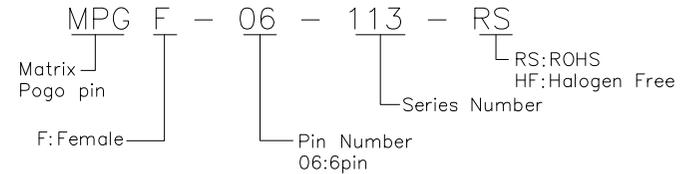
Notes:

- Material  
Pin: Lead free BrassHBI59-1.5B/C6801 ,  
Plated 10u”Au over 50-100u”Ni  
Mylar:High temperature adhesive tape
- Electrical  
Rated Current&Voltage: DC 12V,6.0A  
Contact resistance:<100mΩ
- Operating Temperature: -40 to +85°C  
Humidity Range:10%RH to 90%RH  
Solder Temperature: 260°C±5° 20s±2s  
RoHS ,HF compliant
- Packing:Reel&Carrier



SECTION A-A

MATRIX PART NO:



Matrix Electronics Co., Ltd

<b>TOLERANCE:</b> 0~6.0 ±0.10mm >6~30 ±0.20mm >30~120 ±0.30mm ANGLE: ±3°	<b>DESIGN BY :</b> Hanson Huang	<b>DATE :</b> 2023/03/23	<b>PART NAME:</b> Pogopin com	
	<b>CHECKED BY:</b> Vicky Hsieh	<b>DATE :</b> 2023/03/23	<b>PART NO.</b>	MPGF-06-113-RS
 <b>UNIT: mm [inch]</b>	<b>APPROVED BY1:</b> Richard Hsieh	<b>DATE :</b> 2023/03/23	<b>MOLD NO.</b>	NA
	<b>APPROVED BY2:</b> Richard Hsieh	<b>DATE :</b> 2023/03/23	<b>DRAW NO.</b>	
<b>SCALE:1:1</b> <b>SIZE:A4</b>			<b>SHEET NO.</b>	1 OF 1